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Circuit boards and circuit board assemblies - Design and use - Part 6-2: Land pattern design - Description of land pattern for the most common surface mounted components (SMD)

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/21

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EN IEC 61188-6-2

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March 2021

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English Version

**Circuit boards and circuit board assemblies - Design and use -
Part 6-2: Land pattern design - Description of land pattern for the
most common surface mounted components (SMD)
(IEC 61188-6-2:2021)**

Cartes imprimées et cartes imprimées équipées -
Conception et utilisation - Partie 6-2: Conception de la zone
de report - Description de la zone de report pour les
composants montés en surface (CMS) les plus courants
(IEC 61188-6-2:2021)

Leiterplatten und Flachbaugruppen - Konstruktion und
Anwendung - Teil 6-2: Anschlussflächenbild - Beschreibung
des Anschlussflächenbilds für die meisten
oberflächenmontierbaren Bauelemente (SMD, en: surface
mounted components)
(IEC 61188-6-2:2021)

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Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61188-6-2:2021 (E)**European foreword**

The text of document 91/1637/CDV, future edition 1 of IEC 61188-6-2, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61188-6-2:2021.

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IEC 61188-5-1:2002	NOTE	Harmonized as EN 61188-5-1:2002 (not modified)
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4
IEC 61188-5-5	NOTE	Harmonized as EN 61188-5-5
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-6
IEC 61188-5-8	NOTE	Harmonized as EN 61188-5-8
IEC 61191 (series)	NOTE	Harmonized as EN 61191 (series)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

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NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-
IEC 61188-6-1	-	Circuit boards and circuit board assemblies - Design and use - Part 6-1: Land pattern design - Generic requirements for land pattern on circuit boards	EN IEC 61188-6-1 ¹	-
IEC 61188-6-4	-	Printed boards and printed board assemblies - Design and use - Part 6-4: Land pattern design - Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design	EN IEC 61188-6-4	-
IEC 61191-2	2017	Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies	EN 61191-2	2017

¹ To be published. Stage at the time of publication: prEN IEC 61188-6-1:2020.



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Edition 1.0 2021-02

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Circuit boards and circuit board assemblies – Design and use –
Part 6-2: Land pattern design – Description of land pattern for the most common
surface mounted components (SMD)**

**Cartes imprimées et cartes imprimées équipées – Conception et utilisation –
Partie 6-2: Conception de la zone de report – Description de la zone de report
pour les composants montés en surface (CMS) les plus courants**



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IEC 61188-6-2

Edition 1.0 2021-02

INTERNATIONAL STANDARD

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES –
DESIGN AND USE –****Part 6-2: Land pattern design – Description of land pattern
for the most common surface mounted components (SMD)**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1637/CDV	91/1657/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 6-2: Land pattern design – Description of land pattern for the most common surface mounted components (SMD)

1 Scope

This part of IEC 61188 describes the requirements of design and use for soldering surfaces of land pattern on circuit boards. This document includes land pattern for surface mounted components. These requirements are based on the solder joint requirements of IEC 61191-2:2017.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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IEC 61188-6-1, *Circuit boards and circuit board assemblies – Design and use – Part 6-1: Land pattern design – Generic requirements for land pattern on circuit boards*

IEC 61188-6-4, *Printed boards and printed board assemblies – Design and use – Part 6-4: Land pattern design – Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design*

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